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**CONFIRMATION NO. 7826**

SERIAL NUMBER 10/619,978	FILING DATE 07/14/2003  RULE	CLASS 438	GROUP ART UNIT 1765	ATTORNEY DOCKET NO. 01-125/1C	
<b>APPLICANTS</b>					
Yong-Bae Kim, Cupertino, CA; Philippe Schoenborn, San Mateo, CA;					
<b>** CONTINUING DATA *****</b> <i>K-c</i> This application is a CON of <u>09/898,194</u> 07/02/2001 PAT 6,673,721					
<b>** FOREIGN APPLICATIONS *****</b> <i>none</i> <i>K-c</i>					
<b>IF REQUIRED, FOREIGN FILING LICENSE GRANTED</b> <b>** 12/08/2003</b>					
Foreign Priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no 35 USC 119 (a-d) conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance <i>K-c</i> Verified and Acknowledged Examiner's Signature <i>K-c</i> Initials		STATE OR COUNTRY CA	SHEETS DRAWING 2	TOTAL CLAIMS 5	INDEPENDENT CLAIMS 3
<b>ADDRESS</b> 24319 LSI LOGIC CORPORATION 1621 BARBER LANE MS: D-106 MILPITAS , CA 95035					
<b>TITLE</b> Process for removal of photoresist mask used for making vias in low K carbon-doped silicon oxide dielectric material, and for removal of etch residues from formation of vias and removal of photoresist mask					
FILING FEE	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT		<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees ( Filing ) <input type="checkbox"/> 1.17 Fees ( Processing Ext. of time )		